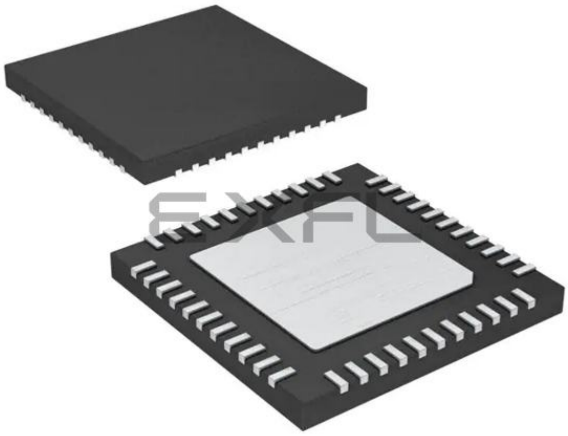

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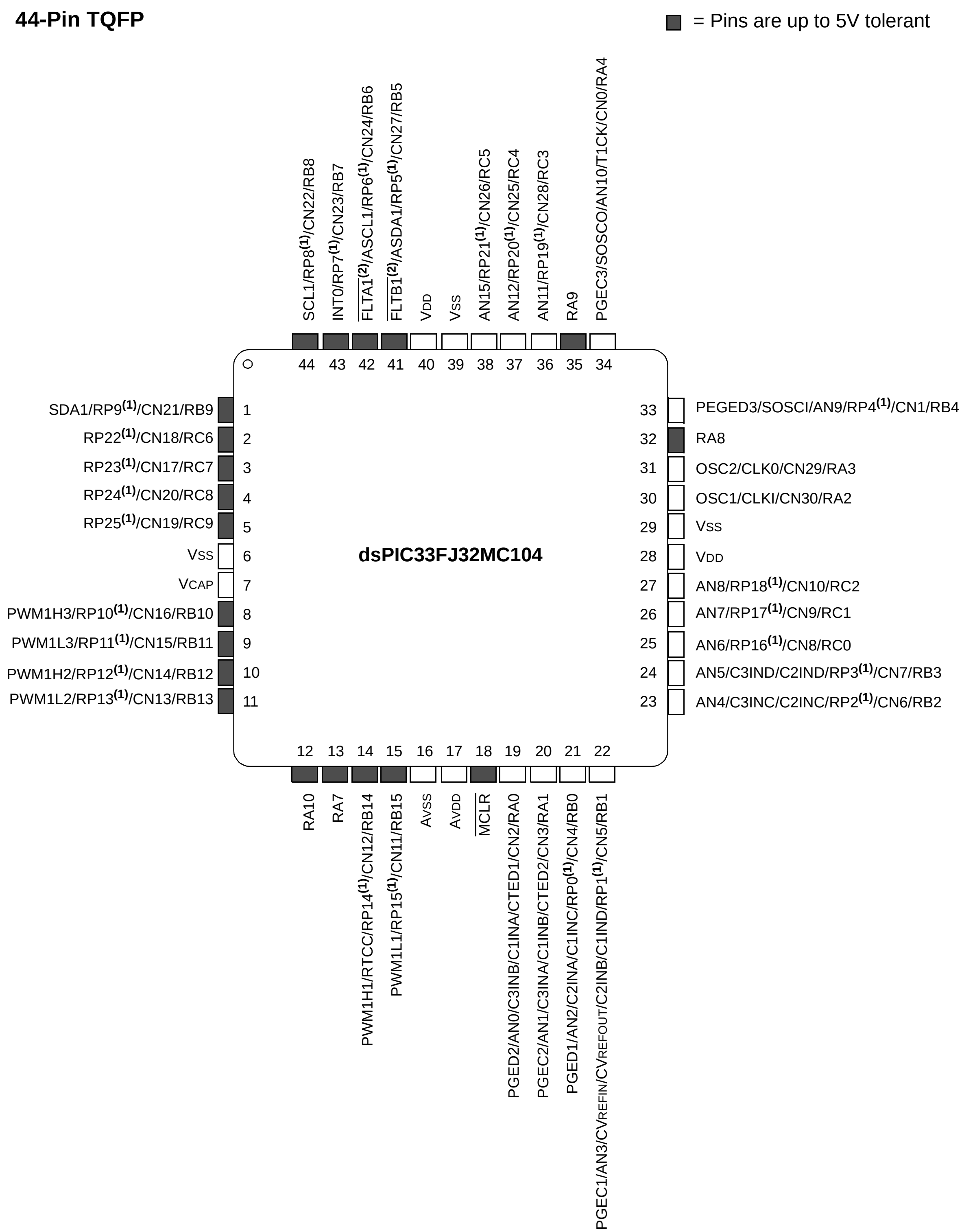
"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	dsPIC
Core Size	16-Bit
Speed	16 MIPs
Connectivity	I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, Motor Control PWM, POR, PWM, WDT
Number of I/O	35
Program Memory Size	32KB (11K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	1K x 16
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 14x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	44-VQFN Exposed Pad
Supplier Device Package	44-QFN (8x8)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33fj32mc104t-e-ml

Pin Diagrams (Continued)



Note 1: The RPn pins can be used by any remappable peripheral. See Table 1 for the list of available peripherals.

2: The PWM Fault pins are enabled and asserted during any Reset event. Refer to **Section 15.2 "PWM Faults"** for more information on the PWM Faults.

3.6.1 MULTIPLIER

The 17-bit x 17-bit multiplier is capable of signed or unsigned operation and can multiplex its output using a scaler to support either 1.31 fractional (Q31) or 32-bit integer results. Unsigned operands are zero-extended into the 17th bit of the multiplier input value. Signed operands are sign-extended into the 17th bit of the multiplier input value. The output of the 17-bit x 17-bit multiplier/scaler is a 33-bit value that is sign-extended to 40 bits. Integer data is inherently represented as a signed 2's complement value, where the Most Significant bit (MSb) is defined as a sign bit. The range of an N-bit 2's complement integer is -2^{N-1} to $2^{N-1} - 1$.

- For a 16-bit integer, the data range is -32768 (0x8000) to 32767 (0x7FFF) including 0.
- For a 32-bit integer, the data range is -2,147,483,648 (0x8000 0000) to 2,147,483,647 (0x7FFF FFFF).

When the multiplier is configured for fractional multiplication, the data is represented as a 2's complement fraction, where the MSb is defined as a sign bit and the radix point is implied to lie just after the sign bit (QX format). The range of an N-bit 2's complement fraction with this implied radix point is -1.0 to $(1 - 2^{1-N})$. For a 16-bit fraction, the Q15 data range is -1.0 (0x8000) to 0.999969482 (0x7FFF) including 0 and has a precision of 3.01518×10^{-5}. In Fractional mode, the 16 x 16 multiply operation generates a 1.31 product that has a precision of 4.65661×10^{-10}.

The same multiplier is used to support the MCU multiply instructions, which include integer 16-bit signed, unsigned and mixed sign multiply operations.

The `MUL` instruction can be directed to use byte or word-sized operands. Byte operands will direct a 16-bit result and word operands will direct a 32-bit result to the specified register(s) in the W array.

3.6.2 DATA ACCUMULATORS AND ADDER/SUBTRACTER

The data accumulator consists of a 40-bit adder/ subtracter with automatic sign extension logic. It can select one of two accumulators (A or B) as its pre-accumulation source and post-accumulation destination. For the `ADD` and `LAC` instructions, the data to be accumulated or loaded can be optionally scaled using the barrel shifter prior to accumulation.

3.6.2.1 Adder/Subtracter, Overflow and Saturation

The adder/subtracter is a 40-bit adder with an optional zero input into one side and either true or complement data into the other input.

- In the case of addition, the Carry/$\overline{\text{Borrow}}$ input is active-high and the other input is true data (not complemented).
- In the case of subtraction, the Carry/$\overline{\text{Borrow}}$ input is active-low and the other input is complemented.

The adder/subtracter generates Overflow Status bits, SA/SB and OA/OB, which are latched and reflected in the STATUS Register:

- Overflow from bit 39: this is a catastrophic overflow in which the sign of the accumulator is destroyed.
- Overflow into guard bits 32 through 39: this is a recoverable overflow. This bit is set whenever all the guard bits are not identical to each other.

The adder has an additional saturation block that controls accumulator data saturation, if selected. It uses the result of the adder, the Overflow Status bits described previously, and the SAT<A:B> (CORCON<7:6>) and ACCSAT (CORCON<4>) mode control bits to determine when and to what value, to saturate.

Six STATUS Register bits support saturation and overflow:

- OA: ACCA overflowed into guard bits
- OB: ACCB overflowed into guard bits
- SA: ACCA saturated (bit 31 overflow and saturation)

  or

  ACCA overflowed into guard bits and saturated (bit 39 overflow and saturation)
- SB: ACCB saturated (bit 31 overflow and saturation)

  or

  ACCB overflowed into guard bits and saturated (bit 39 overflow and saturation)
- OAB: Logical OR of OA and OB
- SAB: Logical OR of SA and SB

The OA and OB bits are modified each time data passes through the adder/subtracter. When set, they indicate that the most recent operation has overflowed into the accumulator guard bits (bits 32 through 39). The OA and OB bits can also optionally generate an arithmetic warning trap when OA and OB are set and the corresponding Overflow Trap Flag Enable bits (OVATE, OVBTE) in the INTCON1 register are set (refer to **Section 7.0 "Interrupt Controller"**). This allows the user application to take immediate action; for example, to correct system gain.

4.0 MEMORY ORGANIZATION

> **Note:** This data sheet summarizes the features of the dsPIC33FJ16(GP/MC)101/102 and dsPIC33FJ32(GP/MC)101/102/104 family devices. However, it is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **"Data Memory"** (DS70202) and **"Program Memory"** (DS70203) in the *"dsPIC33/PIC24 Family Reference Manual"*, which are available from the Microchip web site (www.microchip.com).

The device architecture features separate program and data memory spaces and buses. This architecture also allows the direct access of program memory from the data space during code execution.

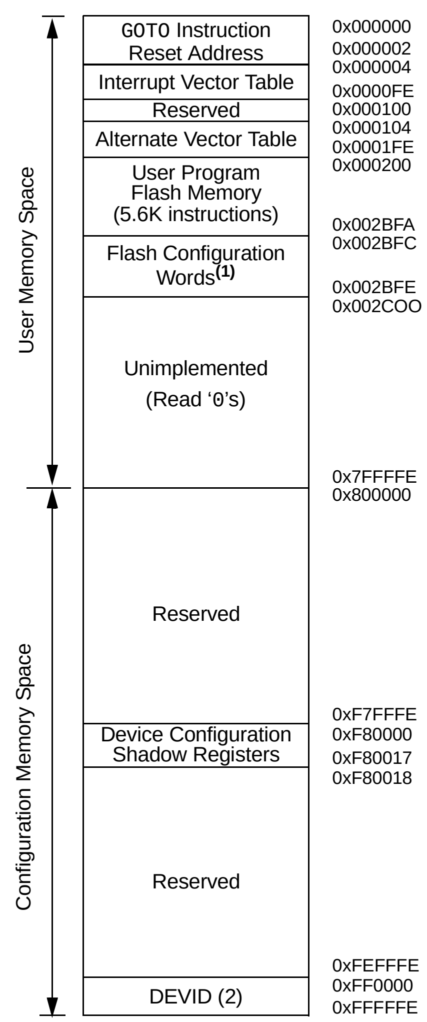
4.1 Program Address Space

The program address memory space of the dsPIC33FJ16(GP/MC)101/102 and dsPIC33FJ32(GP/MC)101/102/104 devices is 4M instructions. The space is addressable by a 24-bit value derived either from the 23-bit Program Counter (PC) during program execution, or from table operation or data space remapping as described in **Section 4.6 "Interfacing Program and Data Memory Spaces"**.

User application access to the program memory space is restricted to the lower half of the address range (0x000000 to 0x7FFFFF). The exception is the use of TBLRD/TBLWT operations, which use TBLPAG<7> to permit access to the Configuration bits and Device ID sections of the configuration memory space.

The memory maps for the dsPIC33FJ16(GP/MC)101/102 and dsPIC33FJ32(GP/MC)101/102/104 family of devices are shown in Figure 4-1 and Figure 4-2.

FIGURE 4-1: PROGRAM MEMORY MAP FOR dsPIC33FJ16(GP/MC)101/102 DEVICES



Note 1: On Reset, these bits are automatically copied into the device Configuration Shadow registers.

TABLE 4-12: I2C1 REGISTER MAP

SFR Name	SFR Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
I2C1RCV	0200	—	—	—	—	—	—	—	—	I2C1 Receive Register								0000
I2C1TRN	0202	—	—	—	—	—	—	—	—	I2C1 Transmit Register								00FF
I2C1BRG	0204	—	—	—	—	—	—	—	Baud Rate Generator Register									0000
I2C1CON	0206	I2CEN	—	I2CSIDL	SCLREL	IPMIEN	A10M	DISSLW	SMEN	GCEN	STREN	ACKDT	ACKEN	RCEN	PEN	RSEN	SEN	1000
I2C1STAT	0208	ACKSTAT	TRSTAT	—	—	—	BCL	GCSTAT	ADD10	IWCOL	I2COV	D_A	P	S	R_W	RBF	TBF	0000
I2C1ADD	020A	—	—	—	—	—	—	I2C1 Address Register										0000
I2C1MSK	020C	—	—	—	—	—	—	I2C1 Address Mask Register										0000

Legend: — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

TABLE 4-13: UART1 REGISTER MAP

SFR Name	SFR Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
U1MODE	0220	UARTEN	—	USIDL	IREN	RTSMD	—	UEN1	UEN0	WAKE	LPBACK	ABAUD	URXINV	BRGH	PDSEL1	PDSEL0	STSEL	0000
U1STA	0222	UTXISEL1	UTXINV	UTXISEL0	—	UTXBRK	UTXEN	UTXBF	TRMT	URXISEL1	URXISEL0	ADDEN	RIDLE	PERR	FERR	OERR	URXDA	0110
U1TXREG	0224	—	—	—	—	—	—	—	UART1 Transmit Register									xxxx
U1RXREG	0226	—	—	—	—	—	—	—	UART1 Receive Register									0000
U1BRG	0228	Baud Rate Generator Prescaler																0000

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

TABLE 4-14: SPI1 REGISTER MAP

SFR Name	SFR Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
SPI1STAT	0240	SPIEN	—	SPISIDL	—	—	—	—	—	—	SPIROV	—	—	—	—	SPITBF	SPIRBF	0000
SPI1CON1	0242	—	—	—	DISSCK	DISSDO	MODE16	SMP	CKE	SSEN	CKP	MSTEN	SPRE2	SPRE1	SPRE0	PPRE1	PPRE0	0000
SPI1CON2	0244	FRMEN	SPIFSD	FRMPOL	—	—	—	—	—	—	—	—	—	—	—	FRMDLY	—	0000
SPI1BUF	0248	SPI1 Transmit and Receive Buffer Register																0000

Legend: — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

TABLE 4-37: SYSTEM CONTROL REGISTER MAP

File Name	SFR Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
RCON	0740	TRAPR	IOPUWR	—	—	—	—	CM	VREGS	EXTR	SWR	SWDTEN	WDTO	SLEEP	IDLE	BOR	POR	xxxx(1)
OSCCON	0742	—	COSC2	COSC1	COSC0	—	NOSC2	NOSC1	NOSC0	CLKLOCK	IOLOCK	LOCK	—	CF	—	LPOSCEN	OSWEN	0300(2)
CLKDIV	0744	ROI	DOZE2	DOZE1	DOZE0	DOZEN	FRCDIV2	FRCDIV1	FRCDIV0	—	—	—	—	—	—	—	—	3040
OSCTUN	0748	—	—	—	—	—	—	—	—	—	—	TUN<5:0>						0000

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: RCON register Reset values are dependent on the type of Reset.

2: OSCCON register Reset values are dependent on the FOSC Configuration bits and by type of Reset.

TABLE 4-38: NVM REGISTER MAP

File Name	SFR Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
NVMCON	0760	WR	WREN	WRERR	—	—	—	—	—	—	ERASE	—	—	NVMOP3	NVMOP2	NVMOP1	NVMOP0	0000(1)
NVMKEY	0766	—	—	—	—	—	—	—	—	NVMKEY<7:0>								0000

Legend: — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: Reset value shown is for POR only. Value on other Reset states is dependent on the state of memory write or erase operations at the time of Reset.

TABLE 4-39: PMD REGISTER MAP

File Name	SFR Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
PMD1	0770	T5MD(2)	T4MD(2)	T3MD	T2MD	T1MD	—	PWM1MD(1)	—	I2C1MD	—	U1MD	—	SPI1MD	—	—	AD1MD	0000
PMD2	0772	—	—	—	—	—	IC3MD	IC2MD	IC1MD	—	—	—	—	—	—	OC2MD	OC1MD	0000
PMD3	0774	—	—	—	—	—	CMPMD	RTCCMD	—	—	—	—	—	—	—	—	—	0000
PMD4	0776	—	—	—	—	—	—	—	—	—	—	—	—	—	CTMUMD	—	—	0000

Legend: — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: This bit is available in dsPIC33FJXXMC10X devices only.

2: These bits are available in dsPIC33FJ32(GP/MC)10X devices only.

6.0 RESETS

> **Note 1:** This data sheet summarizes the features of the dsPIC33FJ16(GP/MC)101/102 and dsPIC33FJ32(GP/MC)101/102/104 family devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **"Reset"** (DS70192) in the "*dsPIC33/PIC24 Family Reference Manual*", which is available from the Microchip web site (www.microchip.com).
>
> **2:** Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The Reset module combines all Reset sources and controls the device Master Reset Signal, $\overline{\text{SYSRST}}$. The following is a list of device Reset sources:

- POR: Power-on Reset
- BOR: Brown-out Reset
- $\overline{\text{MCLR}}$: Master Clear Pin Reset
- SWR: RESET Instruction
- WDTO: Watchdog Timer Reset
- CM: Configuration Mismatch Reset
- TRAPR: Trap Conflict Reset
- IOPUWR: Illegal Condition Device Reset
  - Illegal Opcode Reset
  - Uninitialized W Register Reset
  - Security Reset

A simplified block diagram of the Reset module is shown in Figure 6-1.

Any active source of Reset will make the $\overline{\text{SYSRST}}$ signal active. On system Reset, some of the registers associated with the CPU and peripherals are forced to a known Reset state, and some are unaffected.

> **Note:** Refer to the specific peripheral section or **Section 3.0 "CPU"** of this data sheet for register Reset states.

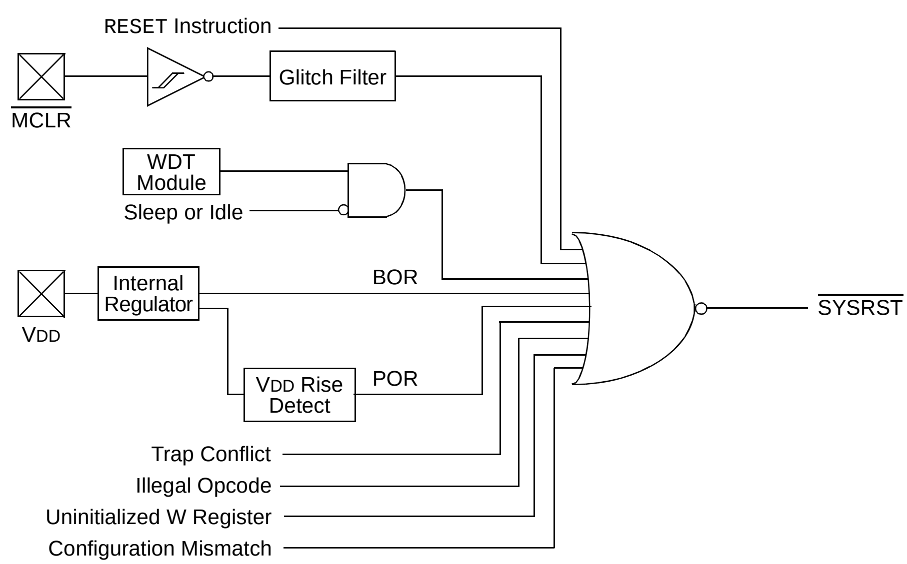
All types of device Reset set a corresponding status bit in the RCON register to indicate the type of Reset (see Register 6-1).

All bits that are set, with the exception of the POR bit (RCON<0>), are cleared during a POR event. The user application can set or clear any bit at any time during code execution. The RCON bits only serve as status bits. Setting a particular Reset status bit in software does not cause a device Reset to occur.

The RCON register also has other bits associated with the Watchdog Timer and device power-saving states. The function of these bits is discussed in other sections of this data sheet.

> **Note:** The status bits in the RCON register should be cleared after they are read so that the next RCON register value after a device Reset is meaningful.

FIGURE 6-1: RESET SYSTEM BLOCK DIAGRAM



8.0 OSCILLATOR CONFIGURATION

Note 1: This data sheet summarizes the features of the dsPIC33FJ16(GP/MC)101/102 and dsPIC33FJ32(GP/MC)101/102/104 family devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **"Oscillator (Part VI)"** (DS70644) in the *"dsPIC33/PIC24 Family Reference Manual"*, which is available from the Microchip web site (www.microchip.com).

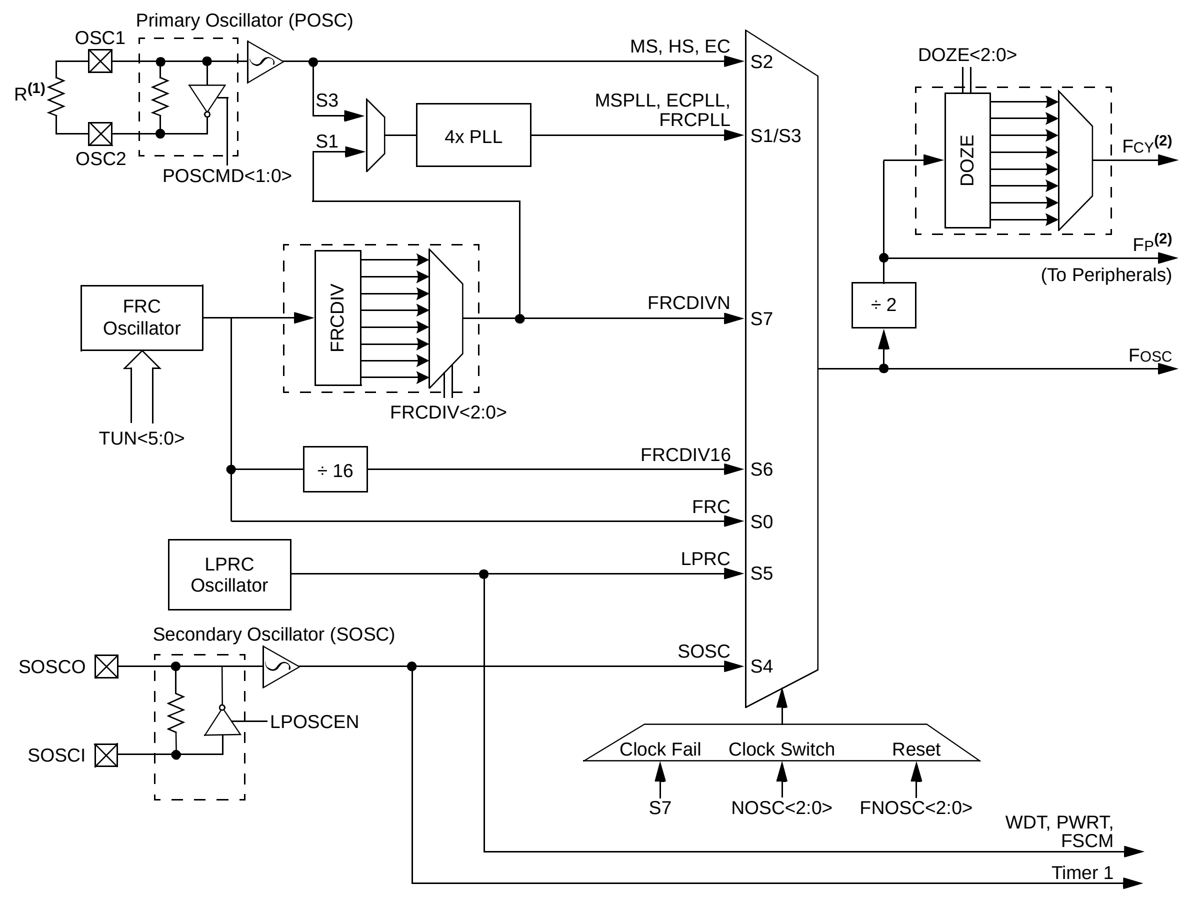
2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The oscillator system for dsPIC33FJ16(GP/MC)101/102 and dsPIC33FJ32(GP/MC)101/102/104 devices provides:

- External and internal oscillator options as clock sources
- An on-chip, 4x Phase Lock Loop (PLL) to scale the internal operating frequency to the required system clock frequency
- An internal FRC oscillator that can also be used with the PLL, thereby allowing full-speed operation without any external clock generation hardware
- Clock switching between various clock sources
- Programmable clock postscaler for system power savings
- A Fail-Safe Clock Monitor (FSCM) that detects clock failure and takes fail-safe measures
- An Oscillator Control register (OSCCON)
- Nonvolatile Configuration bits for main oscillator selection

A simplified diagram of the oscillator system is shown in Figure 8-1.

FIGURE 8-1: OSCILLATOR SYSTEM DIAGRAM



Note 1: If the oscillator is used with MS or HS modes, an extended parallel resistor with the value of 1 MΩ must be connected.

2: The term, FP, refers to the clock source for all peripherals, while FCY refers to the clock source for the CPU. Throughout this document, FCY and FP are used interchangeably, except in the case of Doze mode. FP and FCY will be different when Doze mode is used with a Doze ratio of 1:2 or lower.

10.5 I/O Helpful Tips

1. In some cases, certain pins, as defined in **Section 26.0 "Electrical Characteristics"**, Table 26-11 under "Injection Current", have internal protection diodes to V_{DD} and V_{SS}. The term, "Injection Current", is also referred to as "Clamp Current". On designated pins, with sufficient external current limiting precautions by the user, I/O pin input voltages are allowed to be greater or less than the data sheet absolute maximum ratings with nominal V_{DD}, with respect to the V_{SS} and V_{DD} supplies. Note that when the user application forward biases either of the high or low side internal input clamp diodes, that the resulting current being injected into the device, that is clamped internally by the V_{DD} and V_{SS} power rails, may affect the ADC accuracy by four to six counts.
2. I/O pins that are shared with any analog input pin, (i.e., ANx), are always analog pins by default after any Reset. Consequently, any pin(s) configured as an analog input pin, automatically disables the digital input pin buffer. As such, any attempt to read a digital input pin will always return a '0' regardless of the digital logic level on the pin if the analog pin is configured. To use a pin as a digital I/O pin on a shared ANx pin, the user application needs to configure the ADC1 Port Configuration Low (AD1PCFGL) register in the ADC module, by setting the appropriate bit that corresponds to that I/O port pin, to a '1'. On devices with more than one ADC, both analog pin configurations for both ADC modules must be configured as a digital I/O pin for that pin to function as a digital I/O pin.

Note:	Although it is not possible to use a digital input pin when its analog function is enabled, it is possible to use the digital I/O output function, TRISx = 0x0, while the analog function is also enabled. However, this is not recommended, particularly if the analog input is connected to an external analog voltage source, which would create signal contention between the analog signal and the output pin driver.

3. Most I/O pins have multiple functions. Referring to the device pin diagrams in the data sheet, the priorities of the functions allocated to any pins are indicated by reading the pin name from left-to-right. The left most function name takes precedence over any function to its right in the naming convention. For example: AN16/T2CK/T7CK/RC1. This indicates that AN16 is the highest priority in this example and will supersede all other functions to its right in the list. Those other functions to its right, even if enabled, would not work as long as any other function to its left was enabled. This rule applies to all of the functions listed for a given pin.
4. Each CN pin has a configurable internal weak pull-up resistor. The pull-ups act as a current source connected to the pin and eliminates the need for external resistors in certain applications. The internal pull-up is to ~(V_{DD} – 0.8), not V_{DD}. This is still above the minimum V_{IH} of CMOS and TTL devices.
5. When driving LEDs directly, the I/O pin can source or sink more current than what is specified in the V_{OH}/I_{OH} and V_{OL}/I_{OL} DC characteristic specification. The respective I_{OH} and I_{OL} current rating only applies to maintaining the corresponding output at or above the V_{OH} and at or below the V_{OL} levels. However, for LEDs unlike digital inputs of an externally connected device, they are not governed by the same minimum V_{IH}/V_{IL} levels. An I/O pin output can safely sink or source any current less than that listed in the absolute maximum rating section of the data sheet. For example:

   V_{OH} = 2.4v @ I_{OH} = -6 mA and V_{DD} = 3.3V

   The maximum output current sourced by any 6 mA I/O pin = 15 mA.

   LED source current < 15 mA is technically permitted. Refer to the V_{OH}/I_{OH} specifications in **Section 26.0 "Electrical Characteristics"** for additional information.

10.6 I/O Resources

Many useful resources are provided on the main product page of the Microchip web site for the devices listed in this data sheet. This product page, which can be accessed using this link, contains the latest updates and additional information.

Note:	In the event you are not able to access the product page using the link above, enter this URL in your browser: http://www.microchip.com/wwwproducts/Devices.aspx?dDocName=en554109

10.6.1 KEY RESOURCES

- **"I/O Ports"** (DS70193) in the *"dsPIC33/PIC24 Family Reference Manual"*
- Code Samples
- Application Notes
- Software Libraries
- Webinars
- All related *"dsPIC33/PIC24 Family Reference Manual"* Sections
- Development Tools

14.1 Output Compare Modes

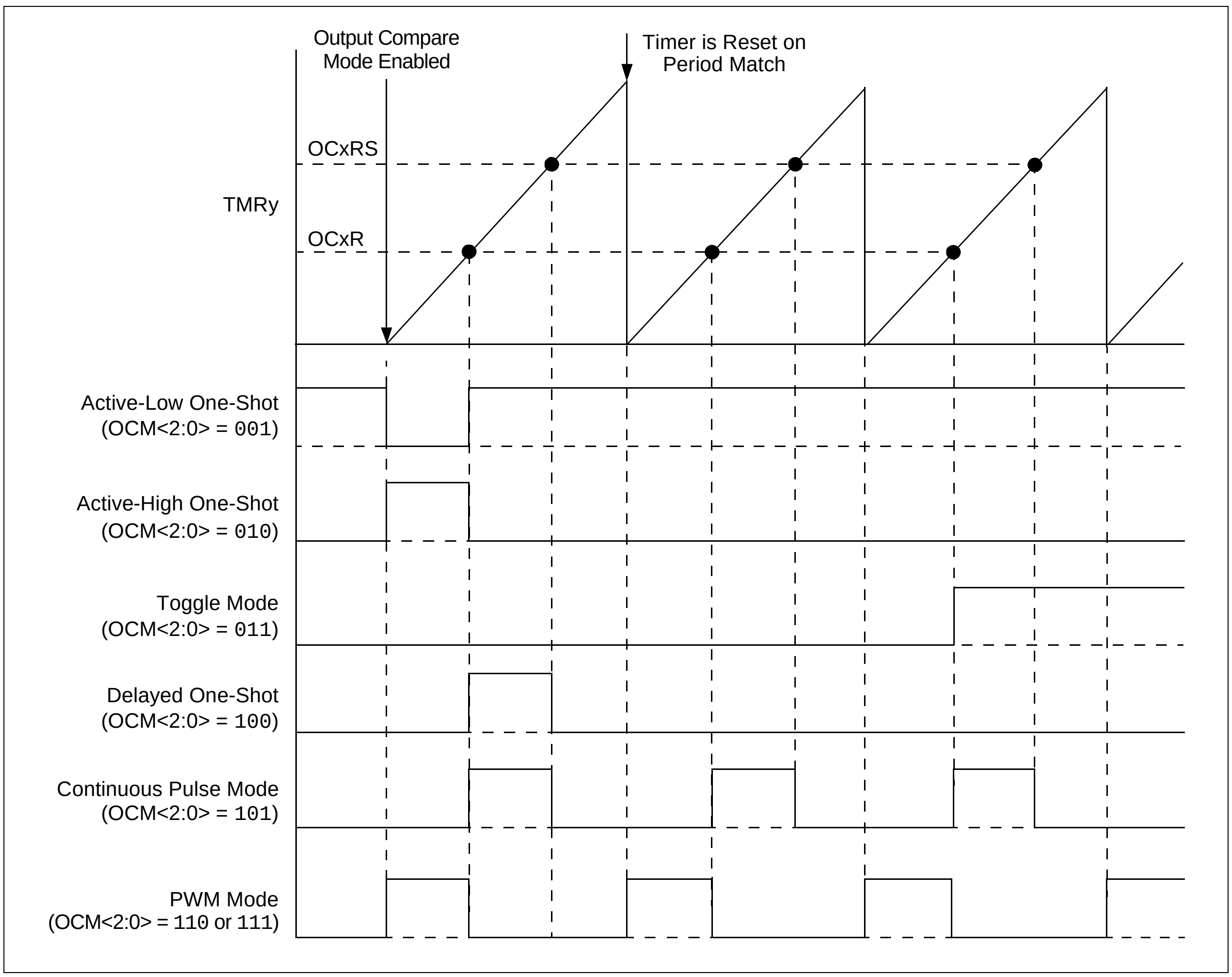
Configure the Output Compare modes by setting the appropriate Output Compare Mode bits (OCM<2:0>) in the Output Compare x Control (OCxCON<2:0>) register. Table 14-1 lists the different bit settings for the Output Compare modes. Figure 14-2 illustrates the output compare operation for various modes. The user application must disable the associated timer when writing to the Output Compare Control registers to avoid malfunctions.

> **Note:** See **"Output Compare"** in the *"dsPIC33/PIC24 Family Reference Manual"* (DS70209) for OCxR and OCxRS register restrictions.

TABLE 14-1: OUTPUT COMPARE x MODES

OCM<2:0>	Mode	OCx Pin Initial State	OCx Interrupt Generation
000	Module Disabled	Controlled by GPIO register	—
001	Active-Low One-Shot	0	OCx Rising Edge
010	Active-High One-Shot	1	OCx Falling Edge
011	Toggle	Current output is maintained	OCx Rising and Falling Edge
100	Delayed One-Shot	0	OCx Falling Edge
101	Continuous Pulse	0	OCx Falling Edge
110	PWM without Fault Protection	0, if OCxR is zero 1, if OCxR is non-zero	No Interrupt
111	PWM with Fault Protection	0, if OCxR is zero 1, if OCxR is non-zero	OCFA Falling Edge for OC1 to OC4

FIGURE 14-2: OUTPUT COMPARE x OPERATION



REGISTER 17-2: I2CxSTAT: I2Cx STATUS REGISTER (CONTINUED)

bit 4	**P:** Stop bit 1 = Indicates that a Stop bit has been detected last 0 = Stop bit was not detected last Hardware sets or clears when Start, Repeated Start or Stop is detected.
bit 3	**S:** Start bit 1 = Indicates that a Start (or Repeated Start) bit has been detected last 0 = Start bit was not detected last Hardware sets or clears when Start, Repeated Start or Stop is detected.
bit 2	**R_W:** Read/Write Information bit (when operating as I^2C slave) 1 = Read – Indicates data transfer is output from slave 0 = Write – Indicates data transfer is input to slave Hardware sets or clears after reception of an I^2C device address byte.
bit 1	**RBF:** Receive Buffer Full Status bit 1 = Receive is complete, I2CxRCV is full 0 = Receive is not complete, I2CxRCV is empty Hardware sets when I2CxRCV is written with received byte. Hardware clears when software reads I2CxRCV.
bit 0	**TBF:** Transmit Buffer Full Status bit 1 = Transmit in progress, I2CxTRN is full 0 = Transmit complete, I2CxTRN is empty Hardware sets when software writes to I2CxTRN. Hardware clears at completion of data transmission.

REGISTER 20-2: CMxCON: COMPARATOR x CONTROL REGISTER

R/W-0	R/W-0	R/W-0	U-0	U-0	U-0	R/W-0	R/W-0
CON	COE	CPOL	—	—	—	CEVT	COUT
bit 15							bit 8

R/W-0	R/W-0	U-0	R/W-0	U-0	U-0	R/W-0	R/W-0
EVPOL1	EVPOL0	—	CREF	—	—	CCH1	CCH0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **CON:** Comparator x Enable bit
1 = Comparator x is enabled
0 = Comparator x is disabled

bit 14 **COE:** Comparator x Output Enable bit
1 = Comparator output is present on the CxOUT pin
0 = Comparator output is internal only

bit 13 **CPOL:** Comparator x Output Polarity Select bit
1 = Comparator x output is inverted
0 = Comparator x output is not inverted

bit 12-10 **Unimplemented:** Read as ‘0’

bit 9 **CEVT:** Comparator x Event bit
1 = Comparator x event according to EVPOL<1:0> settings occurred; disables future triggers and interrupts until the bit is cleared
0 = Comparator x event did not occur

bit 8 **COUT:** Comparator x Output bit
When CPOL = 0 (non-inverted polarity):
1 = $V_{IN}+ > V_{IN}-$
0 = $V_{IN}+ < V_{IN}-$
When CPOL = 1 (inverted polarity):
1 = $V_{IN}+ < V_{IN}-$
0 = $V_{IN}+ > V_{IN}-$

bit 7-6 **EVPOL<1:0>:** Trigger/Event/Interrupt Polarity Select bits
11 = Trigger/event/interrupt is generated on any change of the comparator output (while CEVT = 0)
10 = Trigger/event/interrupt is generated only on high-to-low transition of the polarity selected comparator output (while CEVT = 0)
If CPOL = 1 (inverted polarity):
Low-to-high transition of the comparator output.
If CPOL = 0 (non-inverted polarity):
High-to-low transition of the comparator output.
01 = Trigger/event/interrupt is generated only on low-to-high transition of the polarity selected comparator output (while CEVT = 0)
If CPOL = 1 (inverted polarity):
High-to-low transition of the comparator output.
If CPOL = 0 (non-inverted polarity):
Low-to-high transition of the comparator output.
00 = Trigger/event/interrupt generation is disabled

bit 5 **Unimplemented:** Read as ‘0’

REGISTER 20-2: CMxCON: COMPARATOR x CONTROL REGISTER (CONTINUED)

bit 4 **CREF:** Comparator x Reference Select bit (V_{IN}+ input)
1 = V_{IN}+ input connects to internal CV_{REFIN} voltage
0 = V_{IN}+ input connects to CxINA pin

bit 3-2 **Unimplemented:** Read as ‘0’

bit 1-0 **CCH<1:0>:** Comparator x Channel Select bits
11 = V_{IN}- input of comparator connects to INTREF
10 = V_{IN}- input of comparator connects to CxIND pin
01 = V_{IN}- input of comparator connects to CxINC pin
00 = V_{IN}- input of comparator connects to CxINB pin

26.0 ELECTRICAL CHARACTERISTICS

This section provides an overview of the dsPIC33FJ16(GP/MC)101/102 and dsPIC33FJ32(GP/MC)101/102/104 family electrical characteristics. Additional information will be provided in future revisions of this document as it becomes available.

Absolute maximum ratings for the dsPIC33FJ16(GP/MC)101/102 and dsPIC33FJ32(GP/MC)101/102/104 family are listed below. Exposure to these maximum rating conditions for extended periods may affect device reliability. Functional operation of the device at these, or any other conditions above the parameters indicated in the operation listings of this specification, is not implied.

Absolute Maximum Ratings(1)

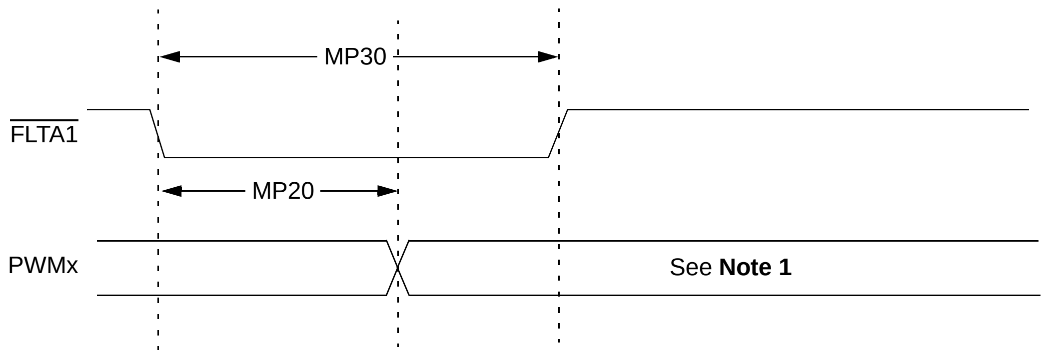
Ambient temperature under bias .... -40°C to +125°C
Storage temperature .... -65°C to +150°C
Voltage on VDD with respect to VSS .... -0.3V to +4.0V
Voltage on any pin that is not 5V tolerant with respect to VSS(3) .... -0.3V to (VDD + 0.3V)
Voltage on any 5V tolerant pin with respect to VSS when VDD ≥ 3.0V(3) .... -0.3V to +5.6V
Voltage on any 5V tolerant pin with respect to VSS when VDD < 3.0V(3) .... -0.3V to (VDD + 0.3V)
Maximum current out of VSS pin .... 300 mA
Maximum current into VDD pin(2) .... 250 mA
Maximum output current sourced and sunk by any I/O pin excluding OSCO .... 15 mA
Maximum output current sourced and sunk by OSCO .... 25 mA
Maximum current sunk by all ports .... 200 mA
Maximum current sourced by all ports(2) .... 200 mA

Note 1: Stresses above those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those, or any other conditions above those indicated in the operation listings of this specification, is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

2: Maximum allowable current is a function of the device maximum power dissipation (see Table 26-2).

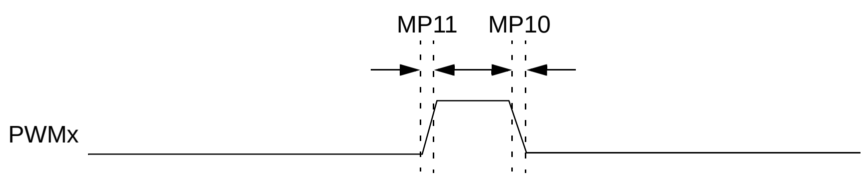
3: See the **“Pin Diagrams”** section for 5V tolerant pins.

FIGURE 26-9: MOTOR CONTROL PWMx MODULE FAULT TIMING CHARACTERISTICS



Note 1: For the logic state after a Fault, refer to the FAOVxH:FAOVxL bits in the PxFLTACON register.

FIGURE 26-10: MOTOR CONTROL PWMx MODULE TIMING CHARACTERISTICS



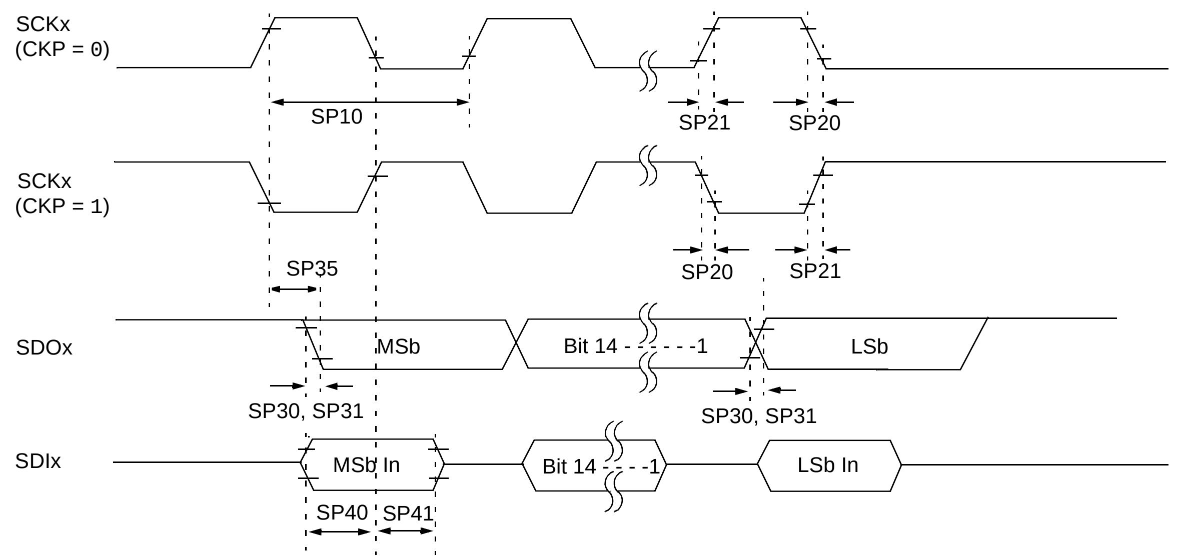
Note: Refer to Figure 26-1 for load conditions.

TABLE 26-28: MOTOR CONTROL PWMx MODULE TIMING REQUIREMENTS

AC CHARACTERISTICS			**Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic(1)**	**Min**	**Typ**	**Max**	**Units**	**Conditions**
MP10	TFPWM	PWM Output Fall Time	—	—	—	ns	See Parameter DO32
MP11	TRPWM	PWM Output Rise Time	—	—	—	ns	See Parameter DO31
MP20	TFD	Fault Input ↓ to PWM I/O Change	—	—	50	ns	
MP30	TFH	Minimum Pulse Width	50	—	—	ns	

Note 1: These parameters are characterized by similarity, but are not tested in manufacturing.

FIGURE 26-14: SPIx MASTER MODE (FULL-DUPLEX, CKE = 0, CKP = x, SMP = 1) TIMING CHARACTERISTICS FOR dsPIC33FJ16(GP/MC)10X



Note: Refer to Figure 26-1 for load conditions.

TABLE 26-32: SPIx MASTER MODE (FULL-DUPLEX, CKE = 0, CKP = x, SMP = 1) TIMING REQUIREMENTS FOR dsPIC33FJ16(GP/MC)10X

AC CHARACTERISTICS			Standard Operating Conditions: 2.4V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	Symbol	Characteristic(1)	Min	Typ(2)	Max	Units	Conditions
SP10	TscP	Maximum SCKx Frequency	—	—	10	MHz	-40°C to +125°C, see **Note 3**
SP20	TscF	SCKx Output Fall Time	—	—	—	ns	See Parameter DO32 and **Note 4**
SP21	TscR	SCKx Output Rise Time	—	—	—	ns	See Parameter DO31 and **Note 4**
SP30	TdoF	SDOx Data Output Fall Time	—	—	—	ns	See Parameter DO32 and **Note 4**
SP31	TdoR	SDOx Data Output Rise Time	—	—	—	ns	See Parameter DO31 and **Note 4**
SP35	TscH2doV, TscL2doV	SDOx Data Output Valid after SCKx Edge	—	6	20	ns	
SP36	TdoV2scH, TdoV2scL	SDOx Data Output Setup to First SCKx Edge	30	—	—	ns	
SP40	TdiV2scH, TdiV2scL	Setup Time of SDIx Data Input to SCKx Edge	30	—	—	ns	
SP41	TscH2diL, TscL2diL	Hold Time of SDIx Data Input to SCKx Edge	30	—	—	ns	

Note 1: These parameters are characterized, but are not tested in manufacturing.

2: Data in “Typ” column is at 3.3V, +25°C unless otherwise stated.

3: The minimum clock period for SCKx is 100 ns. The clock generated in Master mode must not violate this specification.

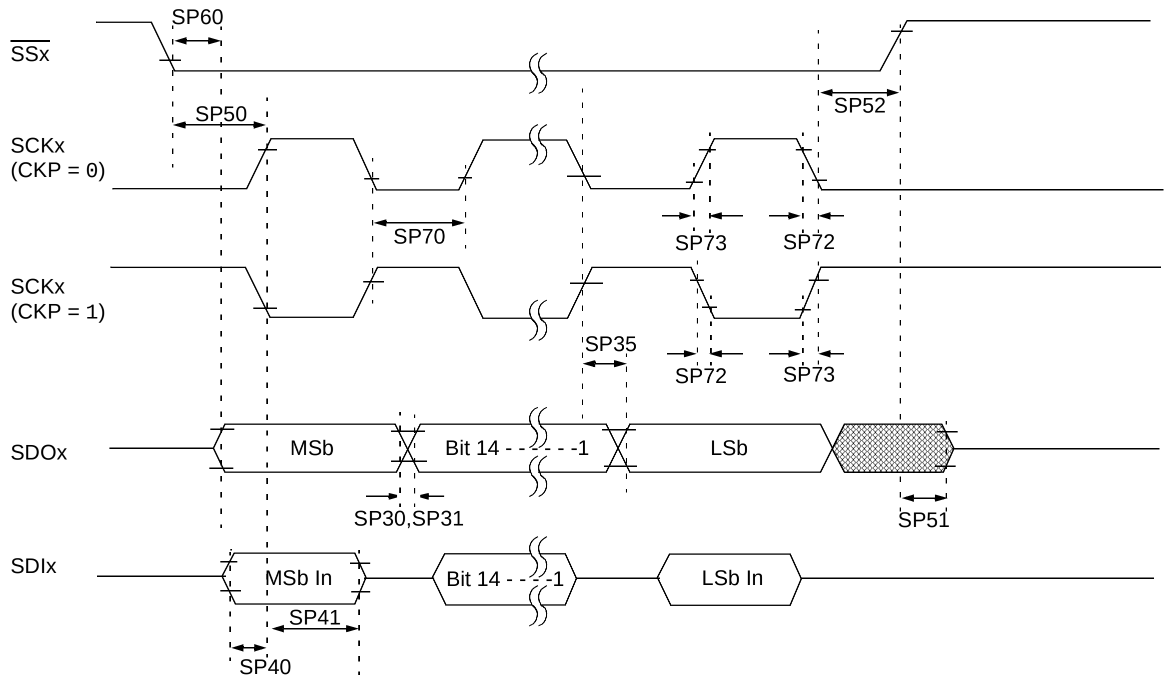
4: Assumes 50 pF load on all SPIx pins.

TABLE 26-36: SPIx SLAVE MODE (FULL-DUPLEX, CKE = 0, CKP = 0, SMP = 0) TIMING REQUIREMENTS FOR dsPIC33FJ16(GP/MC)10X

AC CHARACTERISTICS			Standard Operating Conditions: 2.4V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic(1)**	**Min**	**Typ(2)**	**Max**	**Units**	**Conditions**
SP70	TscP	Maximum SCKx Input Frequency	—	—	11	MHz	See **Note 3**
SP72	TscF	SCKx Input Fall Time	—	—	—	ns	See Parameter DO32 and **Note 4**
SP73	TscR	SCKx Input Rise Time	—	—	—	ns	See Parameter DO31 and **Note 4**
SP30	TdoF	SDOx Data Output Fall Time	—	—	—	ns	See Parameter DO32 and **Note 4**
SP31	TdoR	SDOx Data Output Rise Time	—	—	—	ns	See Parameter DO31 and **Note 4**
SP35	TscH2doV, TscL2doV	SDOx Data Output Valid after SCKx Edge	—	6	20	ns	
SP36	TdoV2scH, TdoV2scL	SDOx Data Output Setup to First SCKx Edge	30	—	—	ns	
SP40	TdiV2scH, TdiV2scL	Setup Time of SDIx Data Input to SCKx Edge	30	—	—	ns	
SP41	TscH2diL, TscL2diL	Hold Time of SDIx Data Input to SCKx Edge	30	—	—	ns	
SP50	TssL2scH, TssL2scL	$\overline{\text{SSx}}$ ↓ to SCKx ↑ or SCKx Input	120	—	—	ns	
SP51	TssH2doZ	$\overline{\text{SSx}}$ ↑ to SDOx Output High-Impedance	10	—	50	ns	See **Note 4**
SP52	TscH2ssH TscL2ssH	$\overline{\text{SSx}}$ after SCKx Edge	1.5 TCY + 40	—	—	ns	See **Note 4**

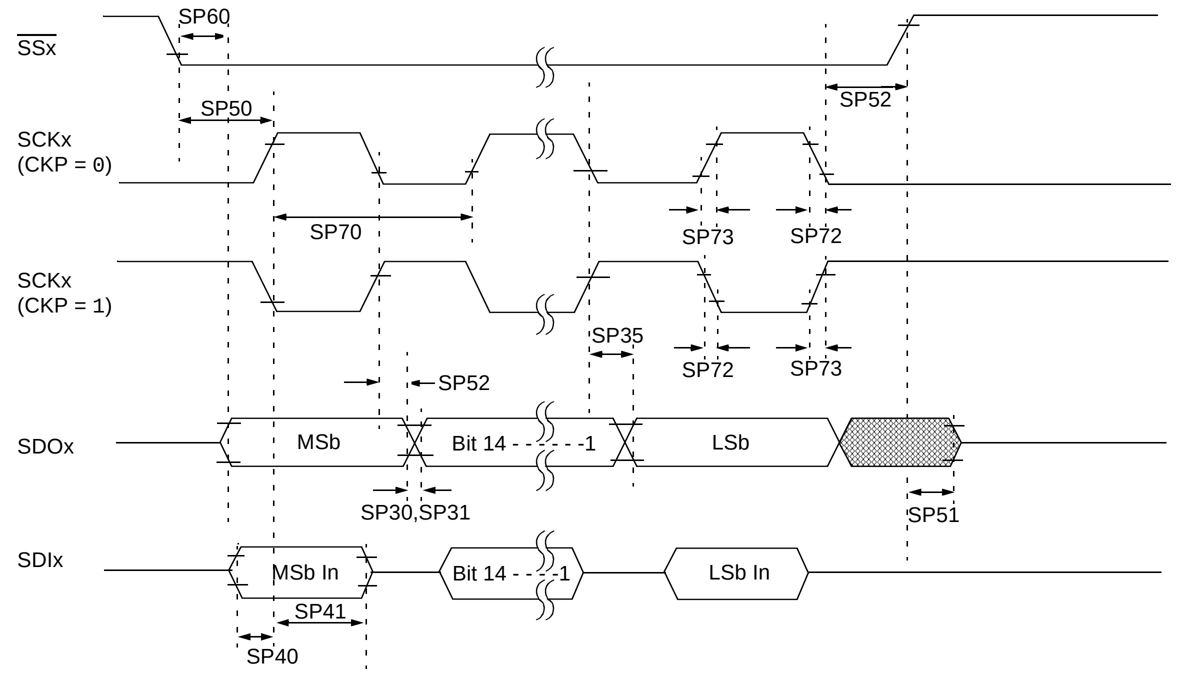
Note 1: These parameters are characterized, but are not tested in manufacturing.
2: Data in “Typ” column is at 3.3V, +25°C unless otherwise stated.
3: The minimum clock period for SCKx is 91 ns. Therefore, the SCKx clock generated by the Master must not violate this specification.
4: Assumes 50 pF load on all SPIx pins.

FIGURE 26-23: SPIx SLAVE MODE (FULL-DUPLEX, CKE = 1, CKP = 0, SMP = 0) TIMING CHARACTERISTICS FOR dsPIC33FJ32(GP/MC)10X



Note: Refer to Figure 26-1 for load conditions.

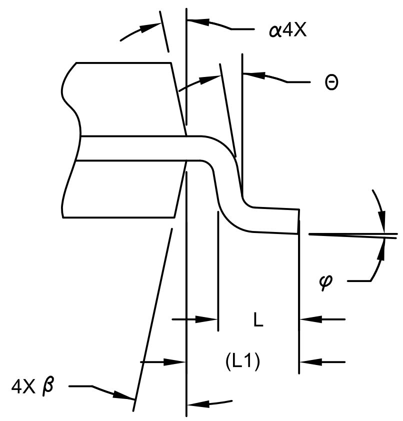
FIGURE 26-24: SPIx SLAVE MODE (FULL-DUPLEX, CKE = 1, CKP = 1, SMP = 0) TIMING CHARACTERISTICS FOR dsPIC33FJ32(GP/MC)10X



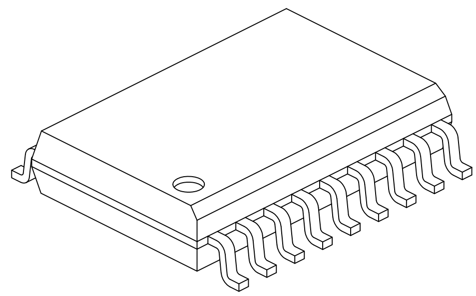
Note: Refer to Figure 26-1 for load conditions.

18-Lead Plastic Small Outline (SO) - Wide, 7.50 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



VIEW C



	Units	MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		18	
Pitch	e		1.27 BSC	
Overall Height	A	-	-	2.65
Molded Package Thickness	A2	2.05	-	-
Standoff §	A1	0.10	-	0.30
Overall Width	E		10.30 BSC	
Molded Package Width	E1		7.50 BSC	
Overall Length	D		11.55 BSC	
Chamfer (Optional)	h	0.25	-	0.75
Foot Length	L	0.40	-	1.27
Footprint	L1		1.40 REF	
Lead Angle	Θ	0°	-	-
Foot Angle	φ	0°	-	8°
Lead Thickness	c	0.20	-	0.33
Lead Width	b	0.31	-	0.51
Mold Draft Angle Top	α	5°	-	15°
Mold Draft Angle Bottom	β	5°	-	15°

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. § Significant Characteristic
3. Dimension D does not include mold flash, protrusions or gate burrs, which shall not exceed 0.15 mm per end. Dimension E1 does not include interlead flash or protrusion, which shall not exceed 0.25 mm per side.
4. Dimensioning and tolerancing per ASME Y14.5M
   BSC: Basic Dimension. Theoretically exact value shown without tolerances.
   REF: Reference Dimension, usually without tolerance, for information purposes only.
5. Datums A & B to be determined at Datum H.

Microchip Technology Drawing No. C04-051C Sheet 2 of 2